

Process For The Manufacture Of A Donor Substrate For The Transfer Of A Piezoelectric Layer And Process For Transfer Of A Piezoelectric Layer Onto A Support Substrate

Abstract

The invention relates to a process for the manufacture of a donor substrate for the transfer of a piezoelectric layer onto a support substrate comprising the stages of providing a handling substrate, in particular a silicon-based substrate, providing a piezoelectric substrate, depositing a polymer layer on a free face of the piezoelectric substrate or of the handling substrate, assembling a piezoelectric substrate on the handling substrate in such a way that the polymer layer is positioned sandwiched between the piezoelectric substrate and the handling substrate, characterized in that a stage of surface activation treatment of the surface of the piezoelectric substrate coming into contact with the polymer layer is carried out before the stage of assembling the piezoelectric substrate on the handling substrate. The invention also relates to a process for the transfer of a piezoelectric layer onto a support substrate.

Figure for the abstract: Figure 1